

20-97 Epoxy Mould Plate

Composition

20-97 mica paper moulding plate is a hot forming plate conforming to NEMA grade 2P. Epoxy resin binder in 20-97 is partially cured, so that it will soften under heat and facilitate good moulding. Also, being extremely flexible, small parts can easily be formed under little pressure without softening the mica paper moulding plate.

Application

Especially recommended for the moulding of small and intricate parts such as caps / rings for the motors for Automobile industry.

Processing

The layout comprising of the required number of layers of thin mica moulding plates (cut to definite shape), is set in a pre determined pattern. It is then heated uniformly to a temperature of 130°C - 150°C, till it becomes soft. It takes the required form when moulded under pressure. It retains its form when cooled under pressure. The duration, temperature and pressure will have to be determined by application.

Product Data

Property	Unit	Value
Thermal Classification	°C	155
Thickness	mm	0.15 – 0.813
Thickness Tolerance	mm	AS per NEMA FI-1-1996 Grade 2P
Binder Content	%	12 - 20
Mouldability		When 2 inch wide strip is heated (135°C - 150°C) & moulded over a mandrel of specified dia. and cooled, moulded form should be retained.
Dielectric Strength	kV/mm	> 20

Shelf Life

Six months at 20°C from the date of manufacturing.

Different Grades

Code No.	Mica paper type	Binder content, %	Milled/Unmilled
20 - 97 -02	Uncalcined muscovite	14 – 20	Unmilled

Available Size of sheets

980 mm X 730 mm ± 10 mm